

74AUP1Z04-Q100

Low-power X-tal driver with enable and internal resistor

Rev. 3 — 17 July 2023

Product data sheet

1. General description

The 74AUP1Z04-Q100 is a crystal driver with enable and internal resistor. When not in use the $\overline{\text{EN}}$ input can be driven HIGH, putting the device in a low power disable mode with X1 pulled HIGH via R_{PU} , X2 set LOW and Y set HIGH. Schmitt trigger action on the $\overline{\text{EN}}$ input makes the circuit tolerant to slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- Wide supply voltage range from 0.8 V to 3.6 V
- CMOS low power dissipation
- High noise immunity
- Overvoltage tolerant inputs to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation at output Y
- Latch-up performance exceeds 100 mA per JESD78B Class II
- Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.65 V to 1.95 V)
 - JESD8-5 (2.3 V to 2.7 V)
 - JESD8C (2.7 V to 3.6 V)
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 3A exceeds 5000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74AUP1Z04GW-Q100	-40 °C to +125 °C	TSSOP6	plastic thin shrink small outline package; 6 leads; body width 1.25 mm	SOT363-2

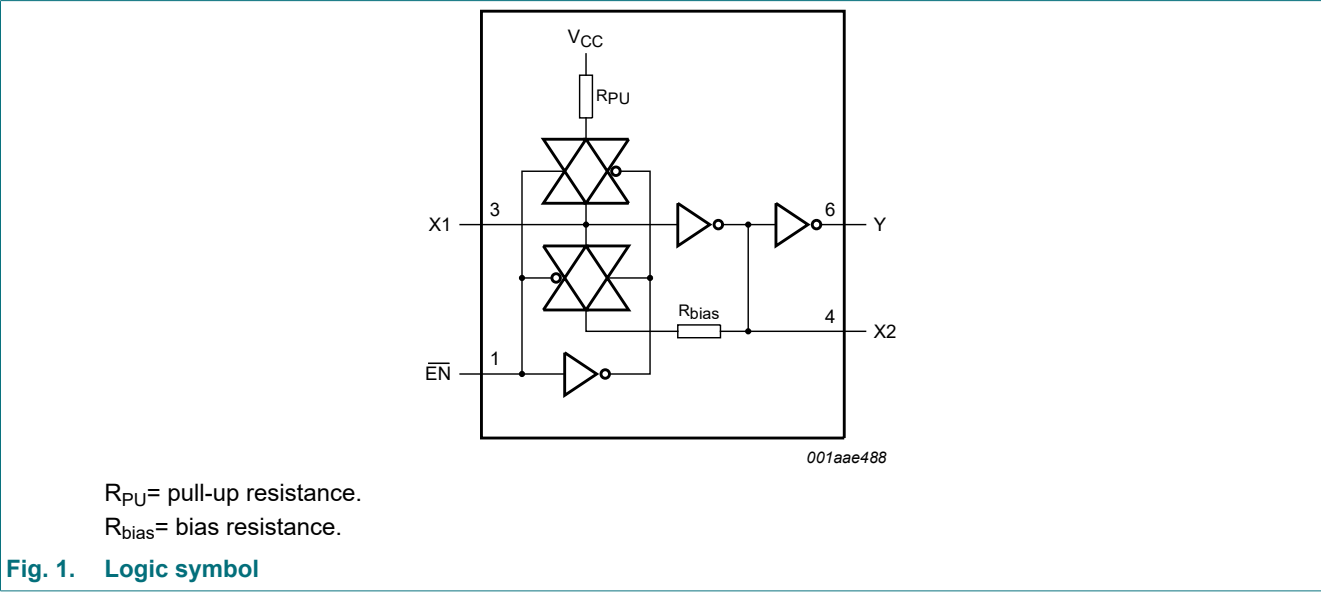
4. Marking

Table 2. Marking

Type number	Marking code ^[1]
74AUP1Z04GW-Q100	a4

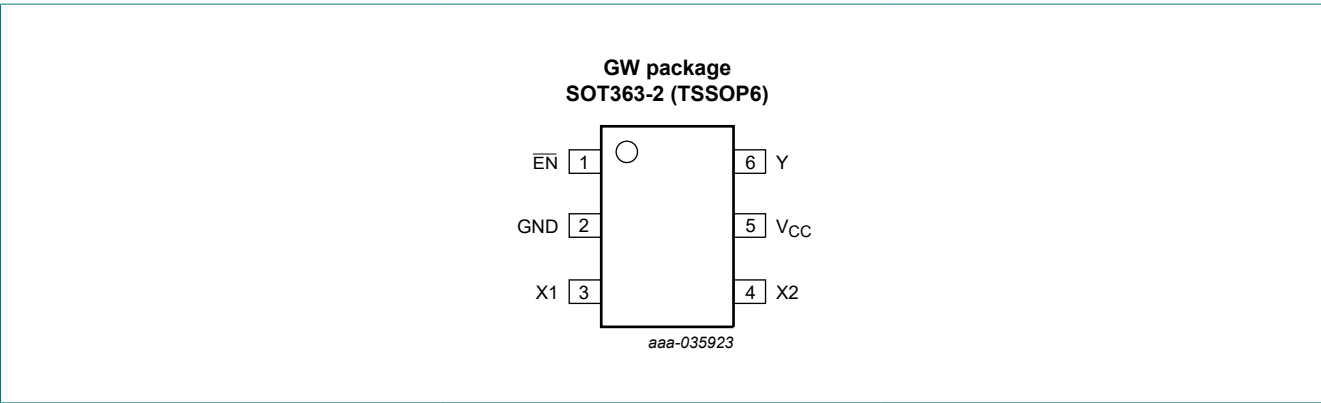
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram



6. Pinning information

6.1. Pinning



6.2. Pin description

Table 3. Pin description

Symbol	Pin	Description
EN	1	enable input (active LOW)
GND	2	ground (0 V)
X1	3	data input
X2	4	data output
V _{CC}	5	supply voltage
Y	6	data output

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level.

Input		Output	
EN	X1	X2	Y
L	L	H	L
L	H	L	H
H	L	H	L
H	H	L	H

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
V _I	input voltage	[1]	-0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
V _O	output voltage	[1]	-0.5	V _{CC} + 0.5	V
I _O	output current	V _O = 0 V to V _{CC}	-	±20	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C [2]	-	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SOT363-2 (TSSOP6) package: P_{tot} derates linearly with 3.7 mW/K above 83 °C.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		0.8	3.6	V
V _I	input voltage		0	3.6	V
V _O	output voltage		0	V _{CC}	V
T _{amb}	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 0.8 V to 3.6 V	-	200	ns/V

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T _{amb} = 25 °C						
V _{IH}	HIGH-level input voltage	X1 input				
		V _{CC} = 0.8 V to 3.6 V	0.75 × V _{CC}	-	-	V
		EN input				
		V _{CC} = 0.8 V	0.70 × V _{CC}	-	-	V
		V _{CC} = 0.9 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.6	-	-	V
		V _{CC} = 3.0 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	X1 input				
		V _{CC} = 0.8 V to 3.6 V	-	-	0.25 × V _{CC}	V
		EN input				
		V _{CC} = 0.8 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{OH}	HIGH-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
		X2 output; V _I = GND or V _{CC}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.75 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.11	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.32	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	2.05	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.9	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.72	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.6	-	-	V
V _{OL}	LOW-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.44	V
		X2 output; V _I = GND or V _{CC}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.31	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.31	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.31	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.44	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.31	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.44	V

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_I	input leakage current	X1 input				
		$V_I = \overline{EN} = V_{CC}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	± 0.1	μA
		$\overline{EN}$ input				
		$V_I = \text{GND to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	± 0.1	μA
I_{pu}	pull-up current	X1 input; $\overline{EN} = V_{CC}$				
		$V_I = \text{GND}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	15	μA
I_{OFF}	power-off leakage current	V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V}$ [1]	-	-	± 0.2	μA
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 0.2 \text{ V}$ [1]	-	-	± 0.2	μA
I_{CC}	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0 \text{ A}; \overline{EN} = \text{GND}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	75	μA
ΔI_{CC}	additional supply current	$\overline{EN}$ input				
		$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	40	μA
C_I	input capacitance	X1 input				
		$V_{CC} = 0 \text{ V to } 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$	-	1.3	-	pF
		$\overline{EN}$ input				
		$V_{CC} = 0 \text{ V to } 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$	-	0.8	-	pF
C_O	output capacitance	X2 output				
		$V_O = \text{GND}; V_{CC} = 0 \text{ V}$	-	1.5	-	pF
		Y output				
		$V_O = \text{GND}; V_{CC} = 0 \text{ V}$	-	1.7	-	pF
g_{fs}	forward transconductance	see Fig. 7 and Fig. 8				
		$V_{CC} = 0.8 \text{ V}$	-	-	-	mA/V
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	0.2	-	9.9	mA/V
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	3.9	-	17.7	mA/V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	7.9	-	24.3	mA/V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	18	-	30.7	mA/V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	20.5	-	32.4	mA/V
R_{bias}	bias resistance	$\overline{EN} = \text{GND}; f_i = 0 \text{ Hz}; V_I = 0 \text{ V or } V_{CC};$ see Fig. 2; for frequency behavior see Fig. 3	1.08	1.62	3.08	M Ω
$T_{amb} = -40 \text{ }^\circ\text{C to } +85 \text{ }^\circ\text{C}$						
V_{IH}	HIGH-level input voltage	X1 input				
		$V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$\overline{EN}$ input				
		$V_{CC} = 0.8 \text{ V}$	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6	-	-	V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{IL}	LOW-level input voltage	X1 input				
		V _{CC} = 0.8 V to 3.6 V	-	-	0.25 × V _{CC}	V
		EN input				
		V _{CC} = 0.8 V	-	-	0.30 × V _{CC}	V
		V _{CC} = 0.9 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 3.0 V to 3.6 V	-	-	0.9	V
V _{OH}	HIGH-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.7 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.03	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.30	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.97	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.85	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.67	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.55	-	-	V
		V _I at X1 input = V _{IH} or V _{IL}				
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.1	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.7 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	1.03	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.30	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.97	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.85	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.67	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.55	-	-	V
V _{OL}	LOW-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.37	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V
		X2 output; V _I = GND or V _{CC}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.1	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.3 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.37	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.35	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.33	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.45	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.33	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.45	V

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_I	input leakage current	X1 input				
		$V_I = \overline{EN} = V_{CC}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	± 0.5	μA
		$\overline{EN}$ input				
		$V_I = \text{GND to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 3.6 \text{ V}$	-	-	± 0.5	μA
I_{pu}	pull-up current	X1 input; $\overline{EN} = V_{CC}$				
		$V_I = \text{GND}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	15	μA
I_{OFF}	power-off leakage current	V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V}$ [1]	-	-	± 0.5	μA
ΔI_{OFF}	additional power-off leakage current	V_I or $V_O = 0 \text{ V to } 3.6 \text{ V}; V_{CC} = 0 \text{ V to } 0.2 \text{ V}$ [1]	-	-	± 0.6	μA
I_{CC}	supply current	$V_I = \text{GND or } V_{CC}; I_O = 0 \text{ A}; \overline{EN} = \text{GND}; V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	75	μA
ΔI_{CC}	additional supply current	$\overline{EN}$ input				
		$V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	50	μA
g_{fs}	forward transconductance	see Fig. 7 and Fig. 8				
		$V_{CC} = 0.8 \text{ V}$	-	-	-	mA/V
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	-	-	10.8	mA/V
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	1.8	-	21.2	mA/V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	7.5	-	29.9	mA/V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	15.0	-	38.0	mA/V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	17.8	-	39.2	mA/V
R_{bias}	bias resistance	$\overline{EN} = \text{GND}; f_i = 0 \text{ Hz}; V_I = 0 \text{ V or } V_{CC};$ see Fig. 2; for frequency behavior see Fig. 3	1.07	-	3.11	$\text{M}\Omega$
$T_{amb} = -40 \text{ }^\circ\text{C to } +125 \text{ }^\circ\text{C}$						
V_{IH}	HIGH-level input voltage	X1 input				
		$V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$\overline{EN}$ input				
		$V_{CC} = 0.8 \text{ V}$	$0.75 \times V_{CC}$	-	-	V
		$V_{CC} = 0.9 \text{ V to } 1.95 \text{ V}$	$0.70 \times V_{CC}$	-	-	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6	-	-	V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V
V_{IL}	LOW-level input voltage	X1 input				
		$V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	$0.25 \times V_{CC}$	V
		$\overline{EN}$ input				
		$V_{CC} = 0.8 \text{ V}$	-	-	$0.25 \times V_{CC}$	V
		$V_{CC} = 0.9 \text{ V to } 1.95 \text{ V}$	-	-	$0.30 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	-	0.9	V

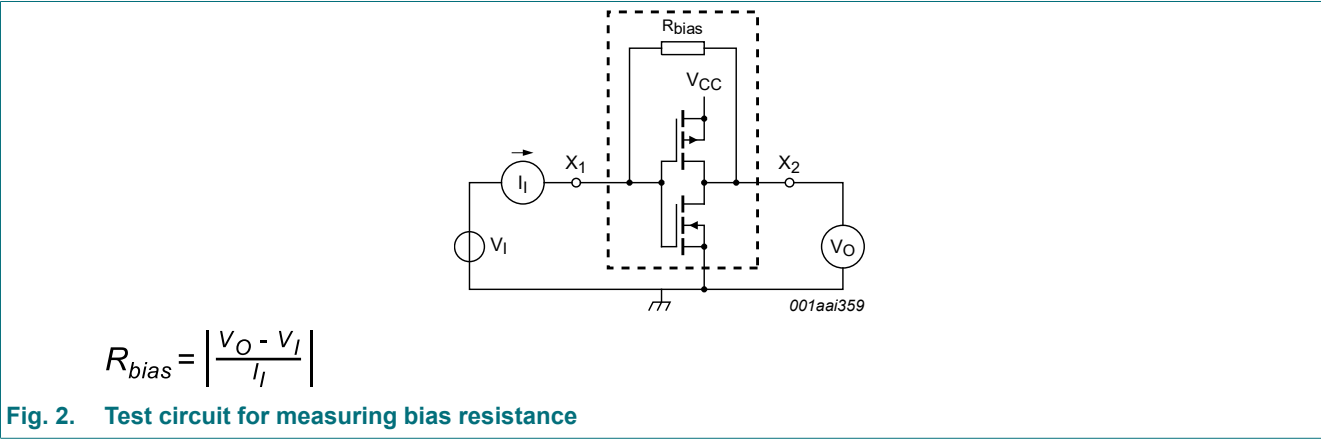
Low-power X-tal driver with enable and internal resistor

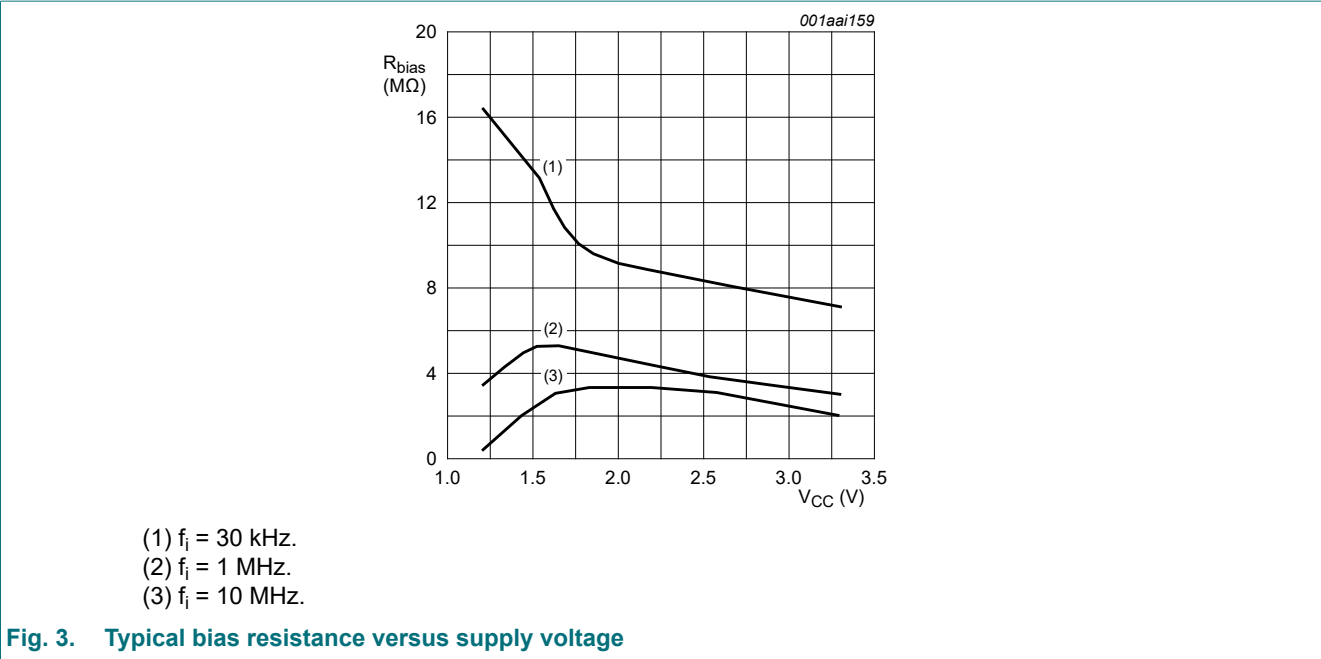
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{OH}	HIGH-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				V
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-	-	V
		X2 output; V _I = GND or V _{CC}				V
		I _O = -20 µA; V _{CC} = 0.8 V to 3.6 V	V _{CC} - 0.11	-	-	V
		I _O = -1.1 mA; V _{CC} = 1.1 V	0.6 × V _{CC}	-	-	V
		I _O = -1.7 mA; V _{CC} = 1.4 V	0.93	-	-	V
		I _O = -1.9 mA; V _{CC} = 1.65 V	1.17	-	-	V
		I _O = -2.3 mA; V _{CC} = 2.3 V	1.77	-	-	V
		I _O = -3.1 mA; V _{CC} = 2.3 V	1.67	-	-	V
		I _O = -2.7 mA; V _{CC} = 3.0 V	2.40	-	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.30	-	-	V
V _{OL}	LOW-level output voltage	Y output; V _I at X1 input = V _{IH} or V _{IL}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V
		X2 output; V _I = GND or V _{CC}				
		I _O = 20 µA; V _{CC} = 0.8 V to 3.6 V	-	-	0.11	V
		I _O = 1.1 mA; V _{CC} = 1.1 V	-	-	0.33 × V _{CC}	V
		I _O = 1.7 mA; V _{CC} = 1.4 V	-	-	0.41	V
		I _O = 1.9 mA; V _{CC} = 1.65 V	-	-	0.39	V
		I _O = 2.3 mA; V _{CC} = 2.3 V	-	-	0.36	V
		I _O = 3.1 mA; V _{CC} = 2.3 V	-	-	0.50	V
		I _O = 2.7 mA; V _{CC} = 3.0 V	-	-	0.36	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.50	V

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _I	input leakage current	X1 input				
		V _I = $\overline{\text{EN}}$ = V _{CC} ; V _{CC} = 0 V to 3.6 V	-	-	±0.75	μA
		$\overline{\text{EN}}$ input				
		V _I = GND to 3.6 V; V _{CC} = 0 V to 3.6 V	-	-	±0.75	μA
I _{pu}	pull-up current	X1 input; $\overline{\text{EN}}$ = V _{CC}				
		V _I = GND; V _{CC} = 0.8 V to 3.6 V	-	-	15	μA
I _{OFF}	power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V [1]	-	-	±0.75	μA
ΔI _{OFF}	additional power-off leakage current	V _I or V _O = 0 V to 3.6 V; V _{CC} = 0 V to 0.2 V [1]	-	-	±0.75	μA
I _{CC}	supply current	V _I = GND or V _{CC} ; I _O = 0 A; $\overline{\text{EN}}$ = GND; V _{CC} = 0.8 V to 3.6 V	-	-	75	μA
ΔI _{CC}	additional supply current	$\overline{\text{EN}}$ input				
		V _I = V _{CC} - 0.6 V; I _O = 0 A; V _{CC} = 3.3 V	-	-	75	μA
g _{fs}	forward transconductance	see Fig. 7 and Fig. 8				
		V _{CC} = 0.8 V	-	-	-	mA/V
		V _{CC} = 1.1 V to 1.3 V	-	-	10.8	mA/V
		V _{CC} = 1.4 V to 1.6 V	1.8	-	21.2	mA/V
		V _{CC} = 1.65 V to 1.95 V	6.9	-	29.9	mA/V
		V _{CC} = 2.3 V to 2.7 V	13.4	-	38.0	mA/V
		V _{CC} = 3.0 V to 3.6 V	15.8	-	39.2	mA/V
R _{bias}	bias resistance	$\overline{\text{EN}}$ = GND; f _i = 0 Hz; V _I = 0 V or V _{CC} ; see Fig. 2; for frequency behavior see Fig. 3	1.07	-	3.11	MΩ

[1] Only for output Y and input $\overline{\text{EN}}$.





11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 6.

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ [1]	Max	Min	Max	Min	Max	
C _L = 5 pF										
t _{pd}	propagation delay	X1 to X2; see Fig. 4 [2]								
		V _{CC} = 0.8 V	-	12.8	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	1.2	3.0	3.9	1.2	3.9	1.2	3.9	ns
		V _{CC} = 1.4 V to 1.6 V	1.0	2.2	2.6	1.0	2.7	1.0	2.7	ns
		V _{CC} = 1.65 V to 1.95 V	0.8	1.9	2.3	0.8	2.4	0.8	2.5	ns
		V _{CC} = 2.3 V to 2.7 V	0.7	1.6	1.9	0.7	2.0	0.7	2.0	ns
		V _{CC} = 3.0 V to 3.6 V	0.7	1.4	1.6	0.7	1.7	0.7	1.7	ns
		X1 to Y; see Fig. 5 [2]								
		V _{CC} = 0.8 V	-	39.2	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.5	8.0	10.7	2.3	10.8	2.3	10.9	ns
		V _{CC} = 1.4 V to 1.6 V	2.2	5.5	6.6	2.0	7.0	2.0	7.0	ns
		V _{CC} = 1.65 V to 1.95 V	1.8	4.4	5.5	1.7	5.9	1.7	6.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.5	3.5	4.1	1.4	4.4	1.4	4.5	ns
		V _{CC} = 3.0 V to 3.6 V	1.5	3.1	3.5	1.4	3.8	1.4	3.8	ns

Low-power X-tal driver with enable and internal resistor

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ [1]	Max	Min	Max	Min	Max	
C _L = 10 pF										
t _{pd}	propagation delay	X1 to X2; see Fig. 4 [2]								
		V _{CC} = 0.8 V	-	20.9	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	1.4	4.1	5.4	1.3	5.6	1.3	5.6	ns
		V _{CC} = 1.4 V to 1.6 V	1.3	2.9	3.6	1.2	3.8	1.2	3.8	ns
		V _{CC} = 1.65 V to 1.95 V	1.2	2.5	3.0	1.1	3.2	1.1	3.2	ns
		V _{CC} = 2.3 V to 2.7 V	0.9	2.0	2.4	0.8	2.5	0.8	2.5	ns
		V _{CC} = 3.0 V to 3.6 V	0.9	1.8	2.1	0.8	2.3	0.8	2.3	ns
		X1 to Y; see Fig. 5 [2]								
		V _{CC} = 0.8 V	-	46.6	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.7	9.2	12.4	2.5	12.7	2.5	12.7	ns
		V _{CC} = 1.4 V to 1.6 V	2.5	6.3	7.8	2.2	8.2	2.2	8.2	ns
		V _{CC} = 1.65 V to 1.95 V	2.3	5.0	6.2	2.2	6.7	2.2	6.7	ns
		V _{CC} = 2.3 V to 2.7 V	1.8	4.0	4.7	1.7	5.0	1.7	5.1	ns
		V _{CC} = 3.0 V to 3.6 V	1.9	3.6	4.2	1.8	4.5	1.8	4.5	ns
C _L = 15 pF										
t _{pd}	propagation delay	X1 to X2; see Fig. 4 [2]								
		V _{CC} = 0.8 V	-	28.9	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	1.7	5.2	7.1	1.6	7.2	1.6	7.3	ns
		V _{CC} = 1.4 V to 1.6 V	1.6	3.6	4.4	1.6	4.7	1.6	4.8	ns
		V _{CC} = 1.65 V to 1.95 V	1.3	3.0	3.7	1.3	3.9	1.3	4.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.4	2.9	1.0	3.1	1.0	3.1	ns
		V _{CC} = 3.0 V to 3.6 V	1.1	2.2	2.5	1.0	2.7	1.0	2.7	ns
		X1 to Y; see Fig. 5 [2]								
		V _{CC} = 0.8 V	-	53.9	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.1	10.4	14.2	2.8	14.6	2.8	14.7	ns
		V _{CC} = 1.4 V to 1.6 V	2.9	7.0	8.5	2.7	9.2	2.7	9.3	ns
		V _{CC} = 1.65 V to 1.95 V	2.5	5.6	6.9	2.3	7.4	2.3	7.5	ns
		V _{CC} = 2.3 V to 2.7 V	2.1	4.5	5.4	2.0	5.7	2.0	5.7	ns
		V _{CC} = 3.0 V to 3.6 V	2.3	4.1	4.7	2.1	5.1	2.1	5.1	ns

Symbol	Parameter	Conditions	T _{amb} = 25 °C			T _{amb} = -40 °C to +85 °C		T _{amb} = -40 °C to +125 °C		Unit
			Min	Typ [1]	Max	Min	Max	Min	Max	
C _L = 30 pF										
t _{pd}	propagation delay	X1 to X2; see Fig. 4 [2]								
		V _{CC} = 0.8 V	-	52.8	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.4	8.5	11.8	2.3	12.2	2.3	12.4	ns
		V _{CC} = 1.4 V to 1.6 V	2.2	5.6	6.8	2.0	7.5	2.0	7.6	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	4.5	5.6	1.9	6.2	1.9	6.2	ns
		V _{CC} = 2.3 V to 2.7 V	1.5	3.7	4.2	1.4	4.6	1.4	4.6	ns
		V _{CC} = 3.0 V to 3.6 V	1.7	3.3	3.7	1.6	4.0	1.6	4.2	ns
		X1 to Y; see Fig. 5 [2]								
		V _{CC} = 0.8 V	-	77.6	-	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.7	13.8	19.2	3.3	19.8	3.3	20.1	ns
		V _{CC} = 1.4 V to 1.6 V	3.4	9.2	11.2	3.1	12.2	3.1	12.3	ns
		V _{CC} = 1.65 V to 1.95 V	3.4	7.4	8.8	3.1	9.7	3.1	9.7	ns
		V _{CC} = 2.3 V to 2.7 V	2.6	5.9	6.7	2.4	7.4	2.4	7.4	ns
		V _{CC} = 3.0 V to 3.6 V	3.2	5.4	6.2	2.9	6.7	2.9	6.9	ns
C _L = 5 pF, 10 pF, 15 pF and 30 pF										
C _{PD}	power dissipation capacitance	f _i = 1 MHz; EN = GND; V _I = GND to V _{CC} [3][4][5]								
		V _{CC} = 0.8 V	-	6.8	-	-	-	-	-	pF
		V _{CC} = 1.1 V to 1.3 V	-	12.0	-	-	-	-	-	pF
		V _{CC} = 1.4 V to 1.6 V	-	18.2	-	-	-	-	-	pF
		V _{CC} = 1.65 V to 1.95 V	-	19.2	-	-	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	21.9	-	-	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	24.9	-	-	-	-	-	pF

[1] All typical values are measured at nominal V_{CC}.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] All specified values are the average typical values over all stated loads.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

[5] Feedback current is included in the C_{PD}.

11.1. Waveforms and test circuit

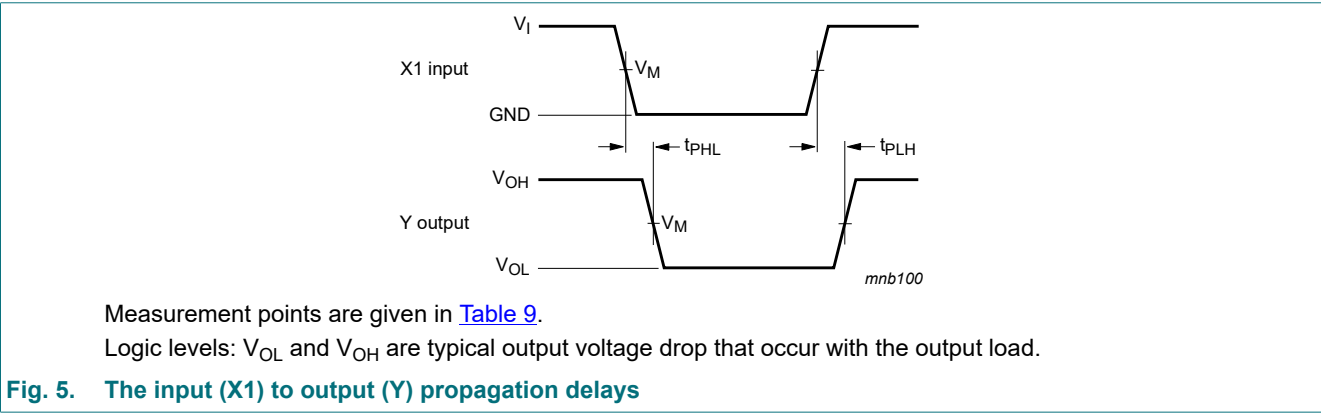
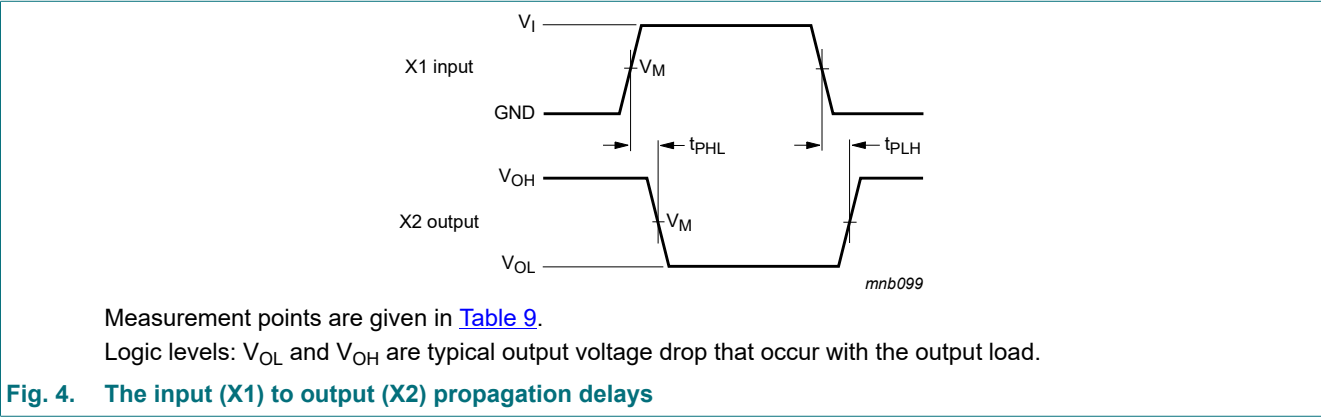
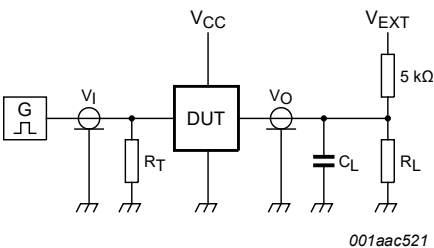


Table 9. Measurement points

Supply voltage	Output	Input		
V_{CC}	V_M	V_M	V_I	$t_r = t_f$
0.8 V to 3.6 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{CC}	$\leq 3.0 \text{ ns}$



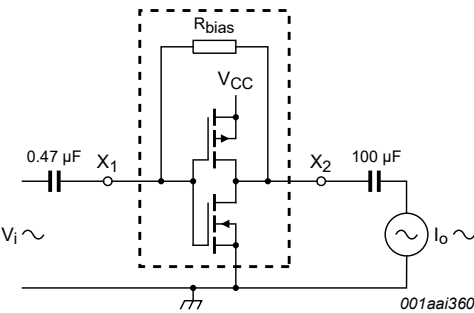
Test data is given in [Table 10](#).
Definitions for test circuit:
 R_L = Load resistance;
 C_L = Load capacitance including jig and probe capacitance;
 R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator;
 V_{EXT} = External voltage for measuring switching times.

Fig. 6. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load		V_{EXT}		
V_{CC}	C_L	R_L [1]	t_{PLH} , t_{PHL}	t_{PZH} , t_{PHZ}	t_{PZL} , t_{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 kΩ or 1 MΩ	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times $R_L = 5\text{ k}\Omega$.
For measuring propagation delays, setup and hold times and pulse width $R_L = 1\text{ M}\Omega$.



$$g_{fs} = \frac{\Delta I_O}{\Delta V_I}$$

$f_i = 1\text{ kHz}$.
 V_O is constant.

Fig. 7. Test set-up for measuring forward transconductance

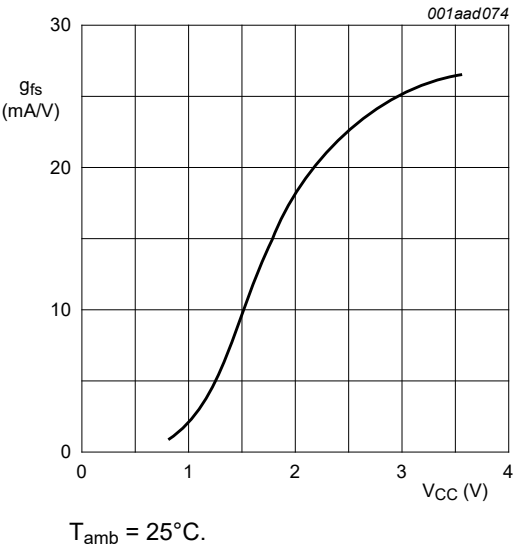


Fig. 8. Typical forward transconductance as a function of supply voltage

12. Application information

Crystal controlled oscillator circuits are widely used in clock pulse generators because of their excellent frequency stability and wide operating frequency range. The use of the 74AUP1Z04-Q100 provides the additional advantages of low power dissipation, stable operation over a wide range of frequency and temperature and a very small footprint. This application information describes crystal characteristics, design and testing of crystal oscillator circuits based on the 74AUP1Z04-Q100.

12.1. Crystal characteristics

Fig. 9 is the equivalent circuit of a quartz crystal.

The reactive and resistive component of the impedance of the crystal alone and the crystal with a series and a parallel capacitance is shown in Fig. 10.

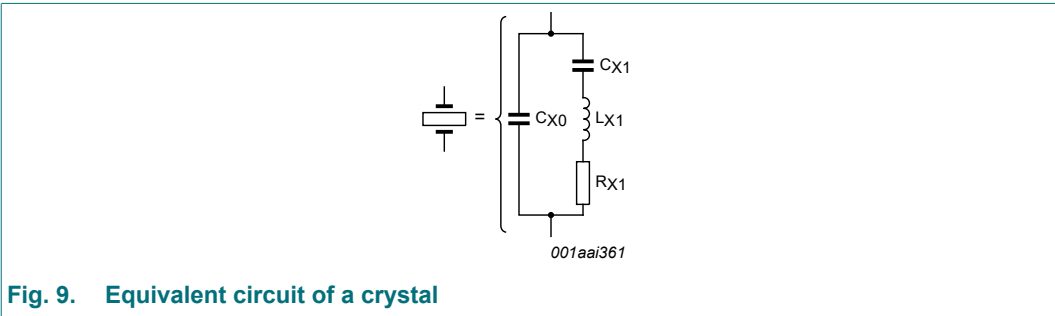


Fig. 9. Equivalent circuit of a crystal

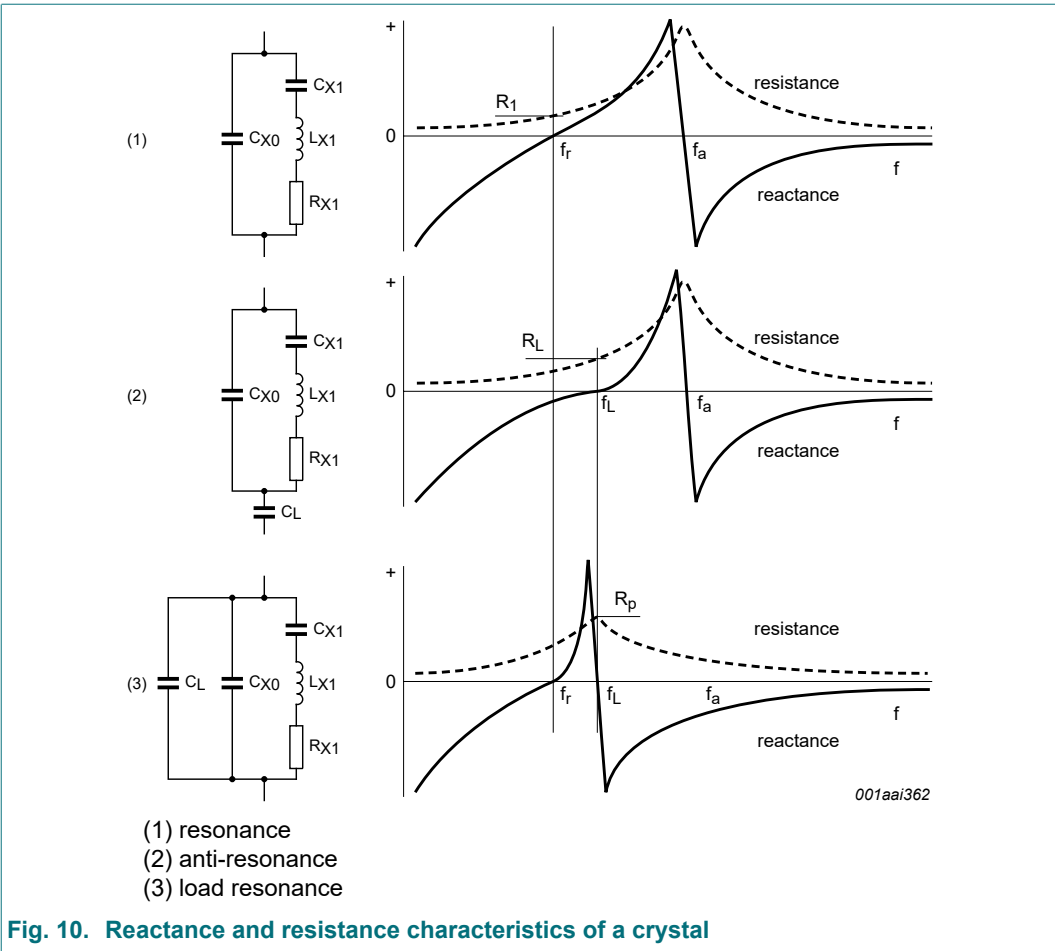


Fig. 10. Reactance and resistance characteristics of a crystal

12.1.1. Design

Fig. 11 shows the recommended way to connect a crystal to the 74AUP1Z04-Q100. This circuit is basically a Pierce oscillator circuit in which the crystal is operating at its fundamental frequency and is tuned by the parallel load capacitance of C_1 and C_2 . C_1 and C_2 are in series with the crystal. They should be approximately equal. R_1 is the drive-limiting resistor and is set to approximately the same value as the reactance of C_1 at the crystal frequency ($R_1 = X_{C1}$). This will result in an input to the crystal of 50 % of the rail-to-rail output of X2. This keeps the drive level into the crystal within drive specifications (the designer should verify this). Overdriving the crystal can cause damage.

The internal bias resistor provides negative feedback and sets a bias point of the inverter near mid-supply, operating the 74AUP1GU04-Q100 portion in the high gain linear region.

To calculate the values of C_1 and C_2 , the designer can use the formula:

$$C_L = \frac{C_1 \times C_2}{C_1 + C_2} + C_s$$

C_L is the load capacitance as specified by the crystal manufacturer, C_s is the stray capacitance of the circuit (for the 74AUP1Z04-Q100 this is equal to an input capacitance of 1.5 pF).

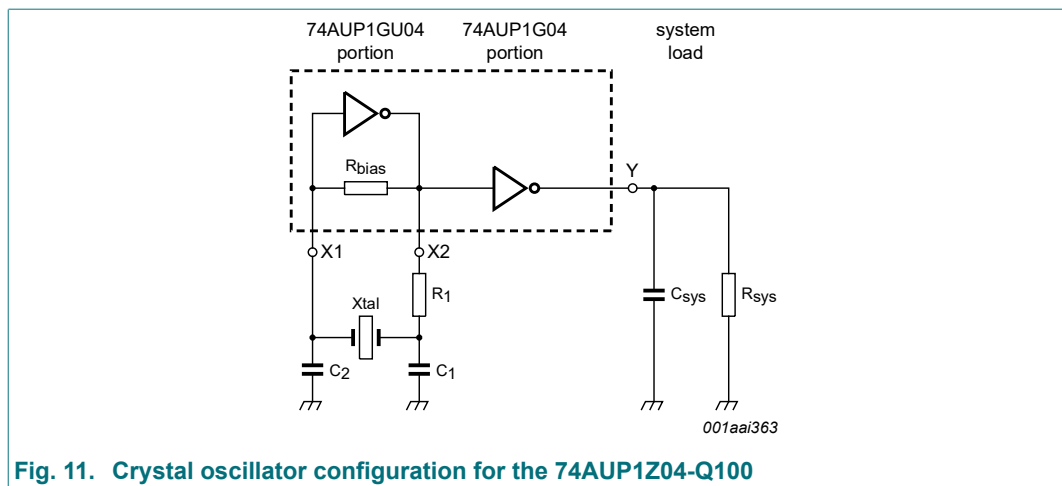


Fig. 11. Crystal oscillator configuration for the 74AUP1Z04-Q100

12.1.2. Testing

After the calculations are performed for a particular crystal, the oscillator circuit should be tested. The following simple checks will verify the prototype design of a crystal controlled oscillator circuit. Perform them after laying out the board:

- Test the oscillator over worst-case conditions (lowest supply voltage, worst-case crystal and highest operating temperature). Adding series and parallel resistors can simulate a worst-case crystal.
- Insure that the circuit does not oscillate without the crystal.
- Check the frequency stability over a supply range greater than that which is likely to occur during normal operation.
- Check that the start-up time is within system requirements.

As the 74AUP1Z04-Q100 isolates the system loading, once the design is optimized, the single layout may work in multiple applications for any given crystal.

13. Package outline

TSSOP6: plastic thin shrink small outline package; 6 leads; body width 1.25 mm SOT363-2

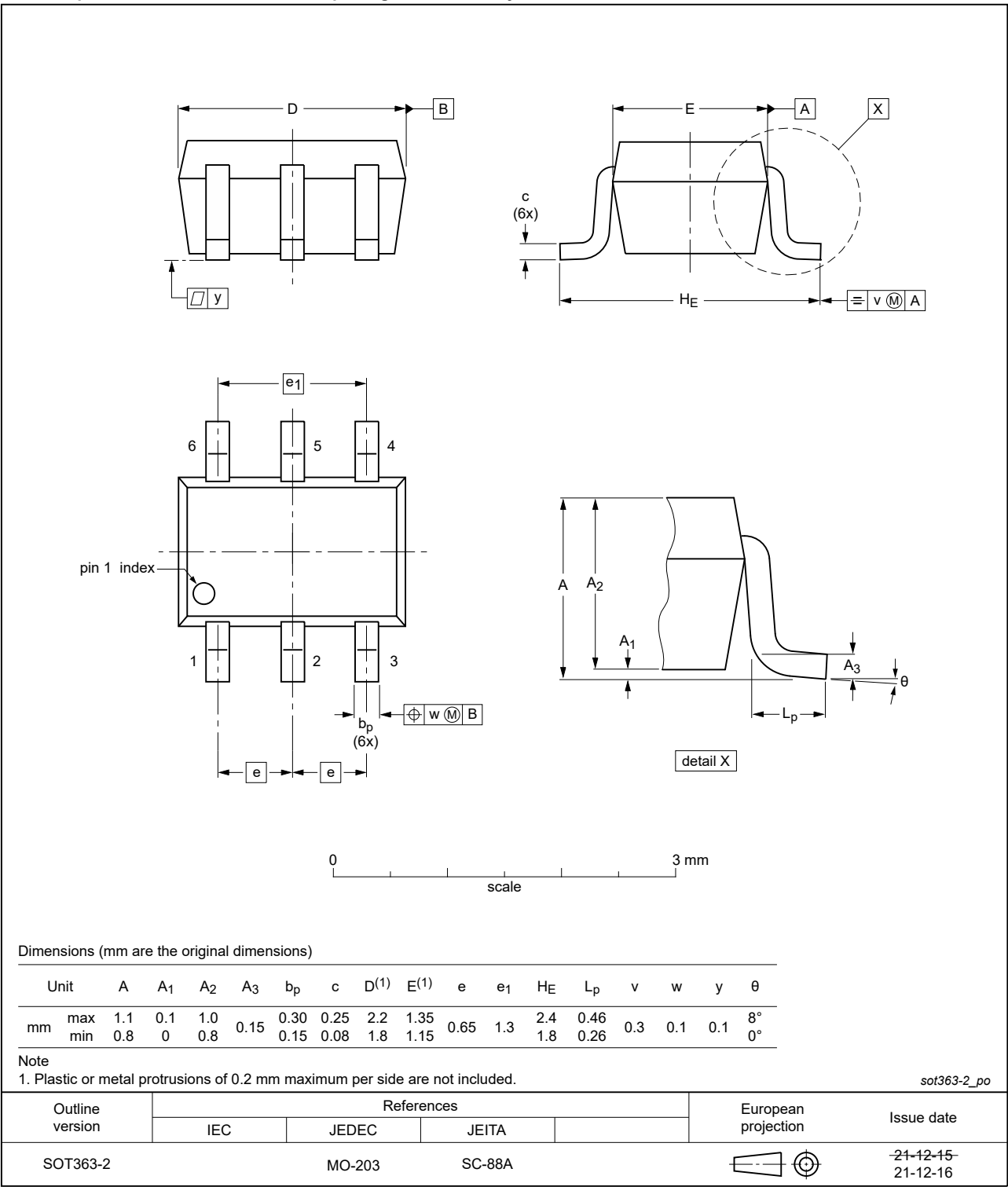


Fig. 12. Package outline SOT363-2 (TSSOP6)

14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1Z04_Q100 v.3	20230717	Product data sheet	-	74AUP1Z04_Q100 v.2
Modifications:	- Section 1 updated. - Section 2: ESD specification updated according to the latest JEDEC standard.			
74AUP1Z04_Q100 v.2	20220127	Product data sheet	-	74AUP1Z04_Q100 v.1
Modifications	SOT363 (SC-88) package changed to SOT363-2 (TSSOP6) package.			
74AUP1Z04_Q100 v.1	20200818	Product data sheet	-	-

16. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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